



Appl. No. 09/858,327  
Amdt. dated Nov. 2, 2004  
Reply to Office Action of Oct. 4, 2004  
Replacement Sheet 1 of 3

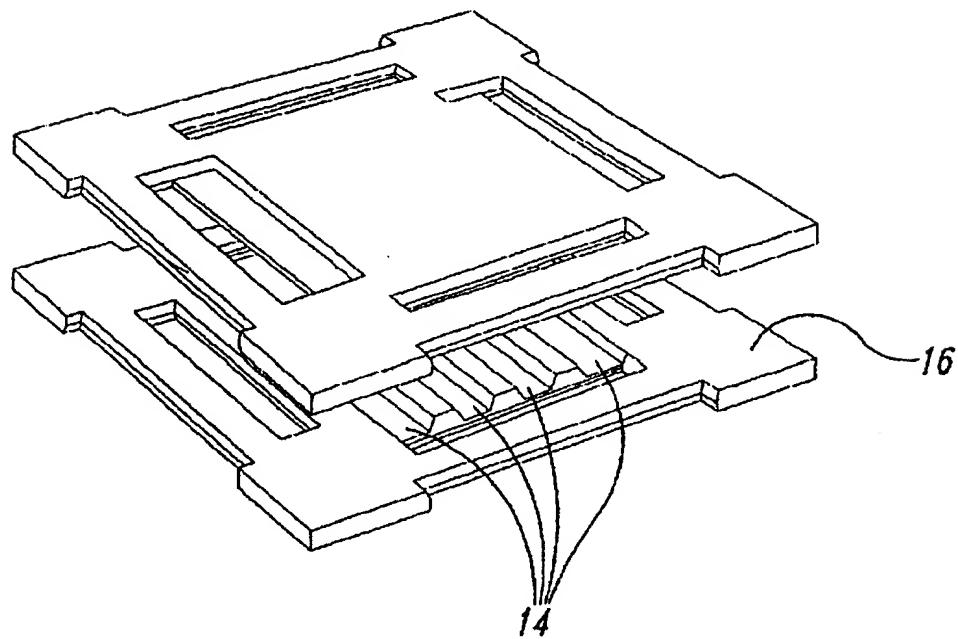


Fig. 1

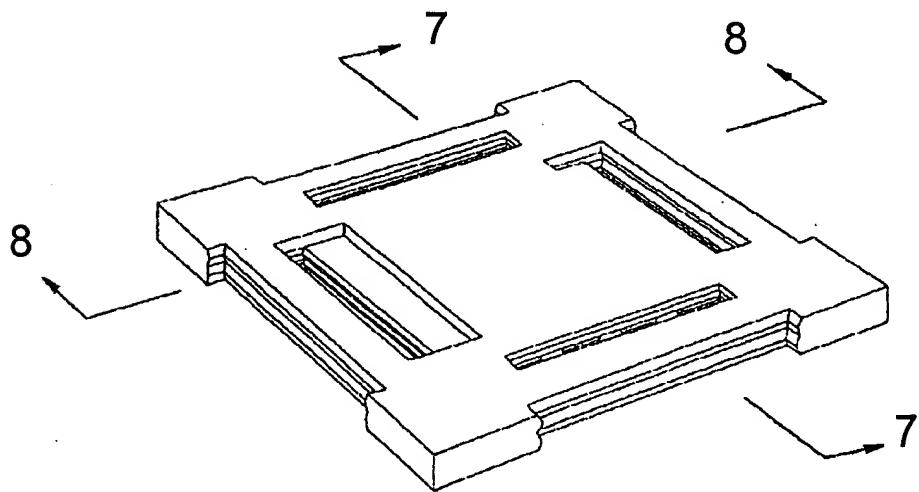


Fig. 2



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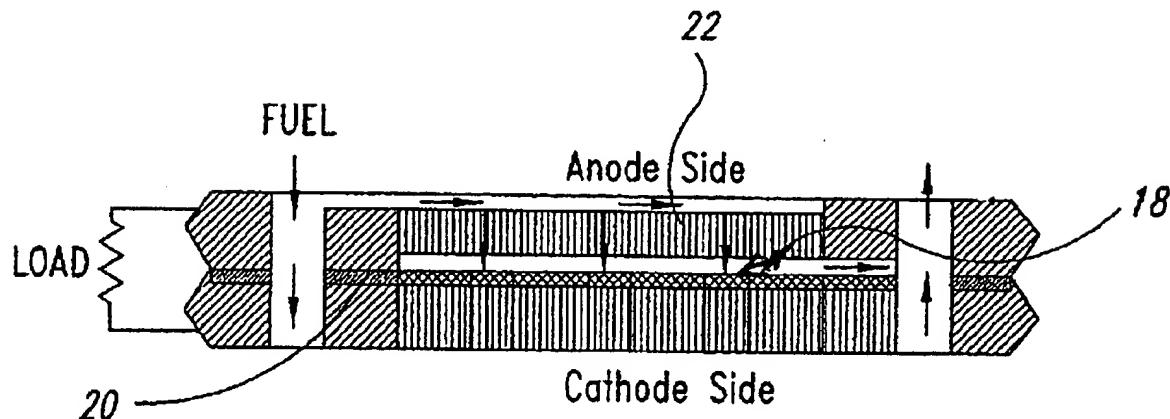
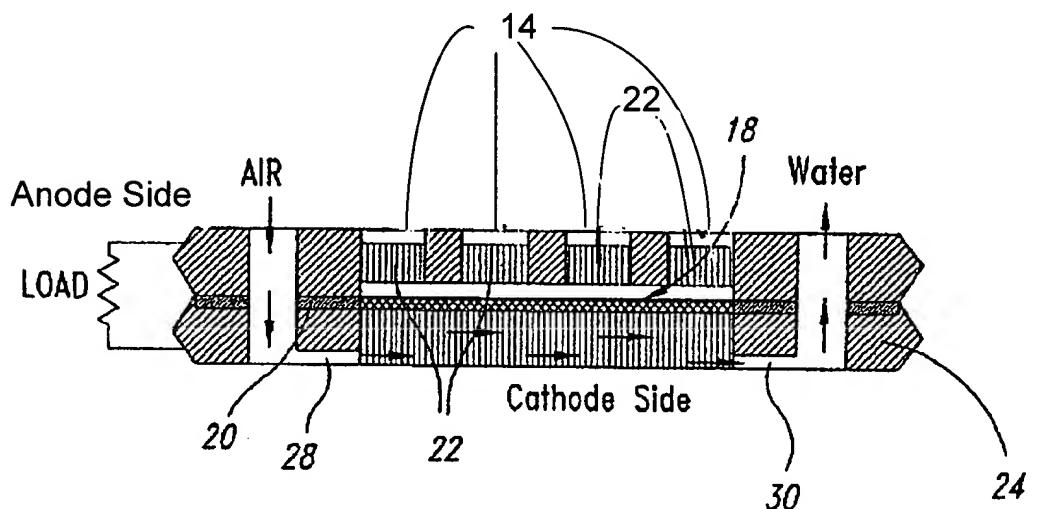


Fig. 3



Flow Channel



Porous Catalyst Region



Silicon Substrate



Methanol Barrier Layer



Wafer Bonding Material

Fig. 4



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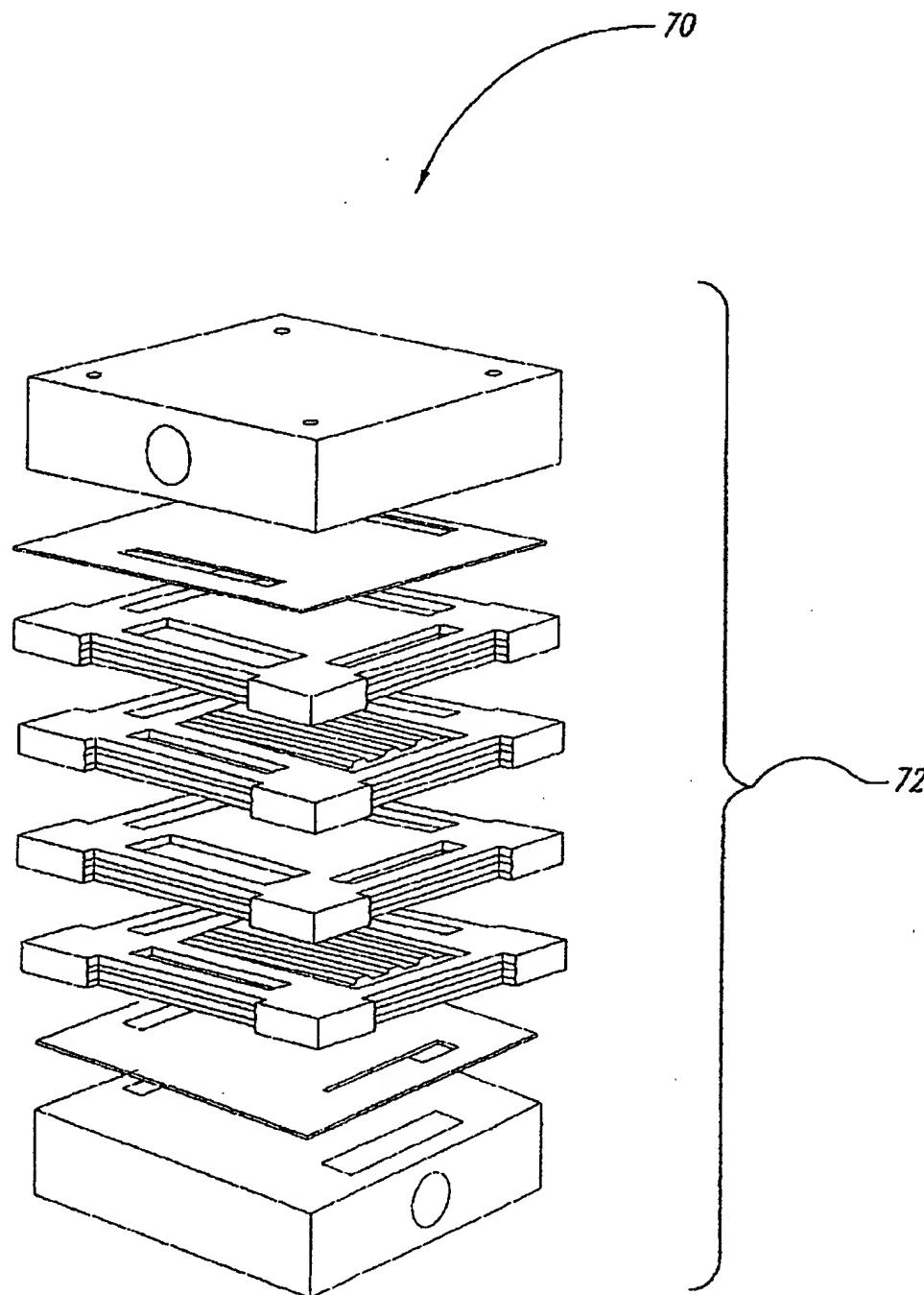


Fig. 5